TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

# 2SK2776

# Chopper Regulator, DC-DC Converter and Motor Drive Applications

• Low drain—source ON resistance : RDS (ON) =  $0.75 \Omega$  (typ.) • High forward transfer admittance :  $|Y_{fs}| = 7.0 S$  (typ.) • Low leakage current : IDSS =  $100 \mu A$  (max) (VDS = 500 V) • Enhancement mode :  $V_{th} = 2.0 \sim 4.0 V$  (VDS = 10 V, ID = 1 mA)

### Absolute Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	500	V	
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)		$V_{DGR}$	500	٧	
Gate-source voltage		V <sub>GSS</sub>	±30	V	
Drain current	DC (Note 1)	ID	8	Α	
	Pulse (Note 1)	I <sub>DP</sub>	32	Α	
Drain power dissipatio	n (Tc = 25°C)	PD	65	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	312	mJ	
Avalanche current		I <sub>AR</sub>	8	Α	
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	6.5	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	1.92	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	83.3	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

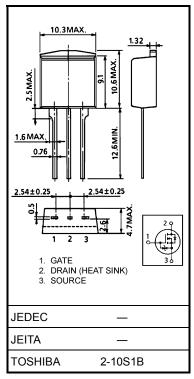
Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 8.3 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 8 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

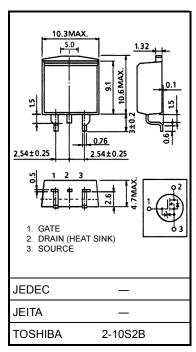
This transistor is an electrostatic-sensitive device.

Please handle with caution.

Unit: mm



Weight: 1.5 g (typ.)



Weight: 1.5 g (typ.)



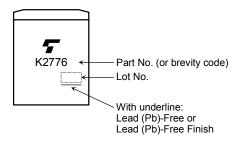
## Electrical Characteristics (Ta = 25°C)

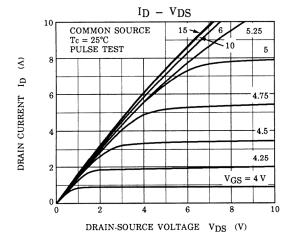
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Gate-source br	eakdown voltage	V (BR) GSS	I <sub>G</sub> = ±10 μA, V <sub>DS</sub> = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	500	_	_	V
Gate threshold	/oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4 A	_	0.75	0.85	Ω
Forward transfe	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 4 A	3.5	7.0	_	S
Input capacitano	ce	C <sub>iss</sub>		-	1300	-	
Reverse transfe	erse transfer capacitance $C_{rss}$ $V_{DS}$ = 10 V, $V_{GS}$ = 0 V, f = 1 MHz		V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		130	_	pF
Output capacitance		C <sub>oss</sub>		_	400	_	
Switching time	Rise time	t <sub>r</sub>	V <sub>GS</sub> <sub>0V</sub>	_	26	_	ns
	Turn-on time	t <sub>on</sub>		_	45	_	
	Fall time	t <sub>f</sub>		_	40	_	
	Turn-off time	t <sub>off</sub>	$V_{\mathrm{DD}} \stackrel{=}{=} 200 \mathrm{V}$ Duty $\leq 1\%$ , $t_{\mathrm{W}} = 10 \mu\mathrm{s}$	_	140	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	30	_	
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 80 \text{ A}$		17	_	nC
Gate-drain ("miller") Charge		Q <sub>gd</sub>			13		

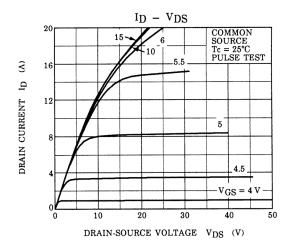
### Source-Drain Ratings and Characteristics (Ta = 25°C)

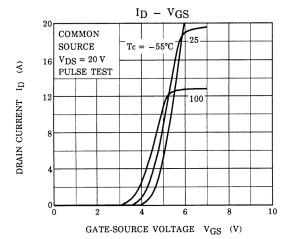
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	8	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	32	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 8 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 8 A, V <sub>GS</sub> = 0 V, dI <sub>DR</sub> / dt = 100 A / μs	_	1200	_	ns
Reverse recovery charge	Q <sub>rr</sub>	1DR - 0 Λ, VGS - 0 V, αιDR / αι - 100 Α / μs	_	10	_	μC

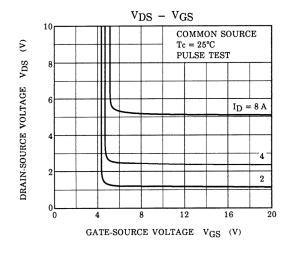
### Marking

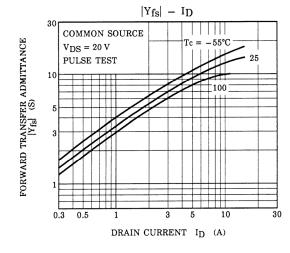


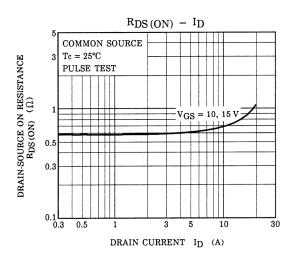


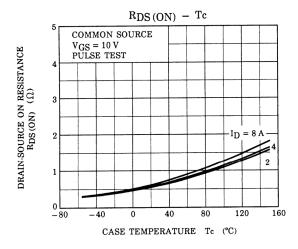


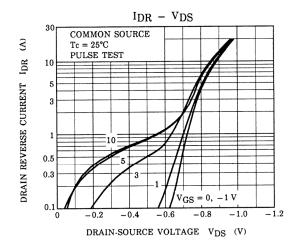


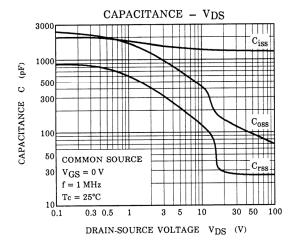


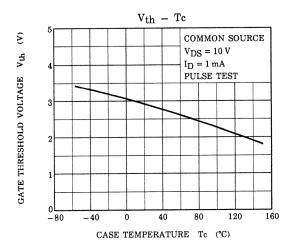


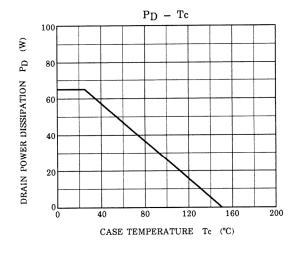


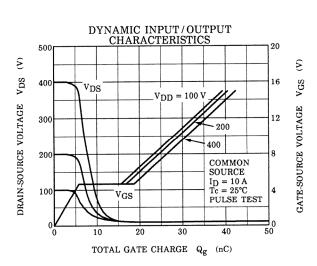




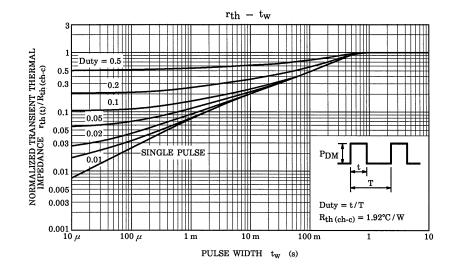


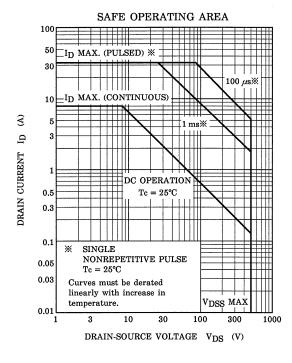


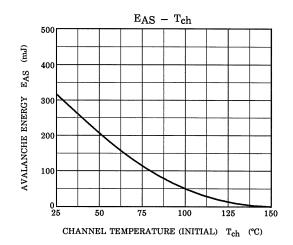


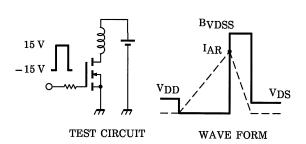


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$$R_G$$
 = 25  $\Omega$   
 $V_{DD}$  = 90 V, L = 8.3 mH

$$EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left( \frac{BVDSS}{BVDSS - VDD} \right)$$

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